



**Statement of Materials, Construction**

64L QFP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy (with silver plating)	0.18432	Cu	7440-50-8	0.17694	23.87	96.00
				Mg	7439-95-4	0.00028	0.04	0.15
				Ni	7440-02-0	0.00553	0.75	3.00
				Si	7440-21-3	0.00120	0.16	0.65
				Silver Plating	7440-22-4	0.00037	0.05	0.20
2	Die	Silicon Chip	0.01002	Si	7440-21-3	0.01002	1.35	99.99
3	Die Attach Material	Conductive Epoxy	0.00794	Silver (Ag)	7440-22-4	0.00603	0.81	76.00
				Epoxy Resin	Proprietary	0.00044	0.06	5.50
				Diester Resin	Proprietary	0.00083	0.11	10.50
				Functionalized Urethane	Proprietary	0.00064	0.09	8.00
4	Wire	Gold	0.00779	Au	7440-57-5	0.00779	1.05	99.99
5	Lead Finish	Alloy	0.00408	Pb	7439-92-1	0.00078	0.11	10.00
				Sn	7440-31-5	0.00367	0.50	90
6	Encapsulation	Epoxy Resin	0.52712	Fused Silica	60676-86-0	0.42961	57.96	81.50
				Epoxy Resin	Proprietary	0.05271	7.11	10.00
				Phenol Resin	Proprietary	0.04217	5.69	8.00
				Carbon Black	1333-86-4	0.00264	0.36	0.50
Total Package Weight =			0.74127					

**Note:** Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%